

C1206X391GATACTU

Aliases (C1206X391GATAC7800) SMD Comm X8G HT150C Flex, Ceramic, 390 pF, 2%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

		Specifications	
	1206	Capacitance	390 pF
	3.3mm +/-0.4mm	Measurement Condition	1 MHz 1.0Vrms
	1.6mm +/-0.35mm	Tolerance	2%
	0.78mm +/-0.20mm	Voltage DC	250 VDC
	1.5mm MIN	Dielectric Withstanding Voltage	625 VDC
	0.6mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
ations		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
	T&R, 180mm, Plastic Tape	Reference to +25°Č and 0 VDC Applied (TCC)	

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Packaging Specifica Pa

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Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

9	Applied (TCC)	
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

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